QUALIFICATION PLAN SUMMARY

PCN #: BLAS-06KHYB542

April 16, 2026

Qualification of QMI519 as an additional die attach material and palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for SST25WF080B-40I/SN, SST25WF040B-40E/SN, SST25WF040B-40I/SN, SST25WF040BT-40E/SN, SST25WF040BT-40I/SN, SST25WF080B-40E/SN, SST25WF080BT-40E/SN and SST25WF080BT-40I/SN catalog part numbers (CPN) available in 8L SOIC (.150in) package at MTAI assembly site.

Purpose: Qualification of QMI519 as an additional die attach material and palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for SST25WF080B-40I/SN, SST25WF040B-40E/SN, SST25WF040B-40I/SN, SST25WF040BT-40E/SN, SST25WF040BT-40I/SN, SST25WF080B-40E/SN, SST25WF080BT-40E/SN and SST25WF080BT-40I/SN catalog part numbers (CPN) available in 8L SOIC (.150in) package at MTAI assembly site.

CCB #: 8240

Misc.	Assembly site	MTAI
	BD Number	BD-004369-01
	MP Code (MPC)	X05024C2XA00
	Part Number (CPN)	SST25WF080B-40E/SN
	MSL information	1
	Assembly Shipping Media (T/R, Tube/Tray)	Tube / T&R
	Base Quantity Multiple (BQM)	100 / 3300
Lead-Frame	Paddle size	95 x 130 mils
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Treatment	BOT
	Process	Stamped
	Lead-lock	Locking Hole
	Part Number	10100842
	Lead Plating	Matte tin
	Strip Size	MTAI standard
	Strip Density	MTAI standard
Bond Wire	Material	CuPdAu
Die Attach	Part Number	QMI519
	Conductive	Yes
MC	Part Number	G600V
PKG	Package Type	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a min. 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5		5	30 bonds from a min. 5 devices.
Wire Sweep								Required for any reduction in wire bond thickness.
Physical Dimensions	Measure per JESD22 B100 and B108	10	0	3	30		5	
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours Electrical test pre and post stress at +25C, 85C and 125C temp.	45	5	3 (Cu wire qual)	150 (Cu wire qual)	0	10	
Preconditioning - Required for surface mount devices MSL 1 @ 260C	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C.	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.
HAST	JESD22-A110. +130°C/85% RH for 96 hours or 110°C/85%RH for 264 hours. Electrical test pre and post stress at +25C, 85C and 125C temp.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
UHAST	JESD22-A118. +130°C/85% RH for 96 hrs or +110°C/85% RH for 264 hrs. Electrical test pre and post stress at +25°C	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles. Electrical test pre and post stress at 85C and 125C temp.; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress.	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.